[ABSTRACT]

This wire bonding apparatus is provided with: a capillary (15), which is driven in the vertical direction by means of a motor (40), and which presses a wire to an electrode; a plate spring (31) wherein a displacement corresponding to a pressing load of the capillary (15) occurs; an angle sensor (52) that detects the displacement of the plate spring (31); and a control unit (60) that adjusts the pressing load of the capillary (15). The control unit (60) presses the plate spring (31) by means of the capillary (15) by applying a current of a predetermined value to the motor (40), detects the displacement of the plate spring (31) by means of the angle sensor (52), and corrects the pressing load of the capillary (15) on the basis of the displacement thus detected. Consequently, the pressing load of the bonding tool can be corrected in succession to a bonding operation with a simple configuration.

FIG. 2